

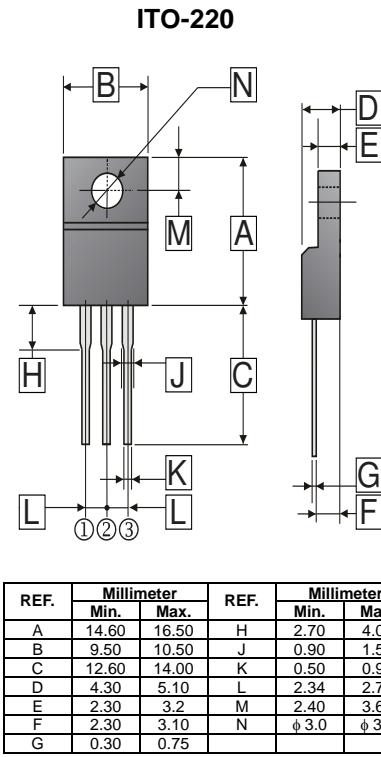
RoHS Compliant Product
A suffix of "-C" specifies halogen free

DESCRIPTION

The SSRF04N60SL is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent R_{DS(on)} and gate charge for most of the synchronous buck converter applications.

FEATURES

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available



ABSOLUTE MAXIMUM RATINGS (T_A=25°C unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	600	V
Gate-Source Voltage	V _{GS}	±30	V
Continuous Drain Current T _C =25°C	I _D	4	A
T _C =100°C		2.5	A
Pulsed Drain Current	I _{DM}	16	A
Total Power Dissipation T _C =25°C	P _D	33	W
Derate above 25°C		0.26	
Single Pulsed Avalanche Energy ¹	E _{AS}	217	mJ
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55~150	°C
Thermal Resistance Rating			
Maximum Thermal Resistance Junction-Ambient	R _{θJA}	120	°C / W
Maximum Thermal Resistance Junction-Case	R _{θJC}	3.85	°C / W

Notes:

1. L=30mH, I_{AS}=3.45A, V_{DD}=155V, R_G=25Ω, Starting T_J=25°C

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static						
Drain-Source Breakdown Voltage	V_{BDSS}	600	-	-	V	$V_{GS}=0$, $I_D= 250\mu\text{A}$
Gate-Threshold Voltage	$V_{GS(\text{th})}$	2	-	4	V	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$
Gate-Source Leakage Current	I_{GSS}	-	-	± 100	nA	$V_{GS}= \pm 30\text{V}$, $V_{DS}=0\text{V}$
Drain-Source Leakage Current	I_{DSS}	-	-	1	μA	$V_{DS}=600\text{V}$, $V_{GS}=0$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	-	2.0	2.4	Ω	$V_{GS}=10\text{V}$, $I_D=2\text{A}$
Total Gate Charge ^{1,2}	Q_g	-	8.16	-	nC	$I_D=4\text{A}$ $V_{DS}=480\text{V}$ $V_{GS}=10\text{V}$
Gate-Source Charge ^{1,2}	Q_{gs}	-	2.63	-		
Gate-Drain Charge ^{1,2}	Q_{gd}	-	3.01	-		
Turn-on Delay Time ^{1,2}	$T_{d(\text{on})}$	-	16.8	-	nS	$V_{DD}=300\text{V}$ $I_D=4\text{A}$ $R_G=25 \Omega$
Rise Time ^{1,2}	T_r	-	26.2	-		
Turn-off Delay Time ^{1,2}	$T_{d(\text{off})}$	-	37.4	-		
Fall Time ^{1,2}	T_f	-	20.2	-		
Input Capacitance	C_{iss}	-	449.7	-	pF	$V_{GS}=0$ $V_{DS}=25\text{V}$ $f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	-	57	-		
Reverse Transfer Capacitance	C_{rss}	-	2.0	-		
Source-Drain Diode						
Diode Forward Voltage	V_{SD}	-	-	1.4	V	$I_S=4\text{A}$, $V_{GS}=0$
Continuous Source Current	I_S	-	-	4	A	Integral Reverse P-N Junction Diode in the MOSFET
Pulsed Source Current	I_{SM}	-	-	16	A	
Reverse Recovery Time	T_{rr}	-	441.53	-	nS	$I_S=4\text{A}$, $V_{GS}=0$, $dI_F/dt=100\text{A}/\mu\text{s}$
Reverse Recovery Charge	Q_{rr}	-	1.98	-	μC	

Notes:

1. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$
2. Essentially independent of operating temperature.

CHARACTERISTIC CURVES

Figure 1. On-Region Characteristics

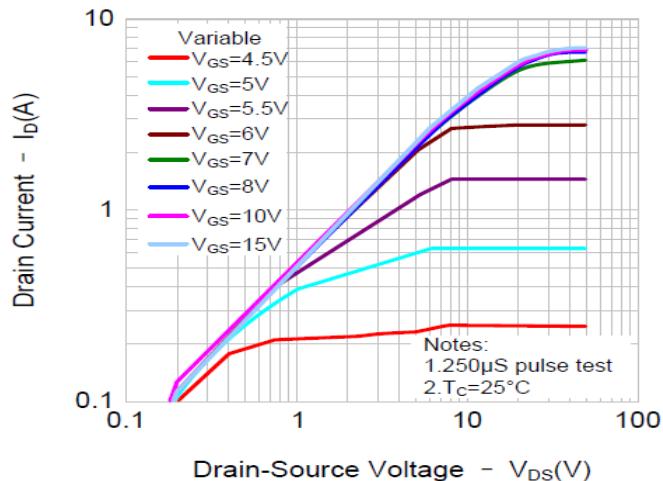


Figure 2. Transfer Characteristics

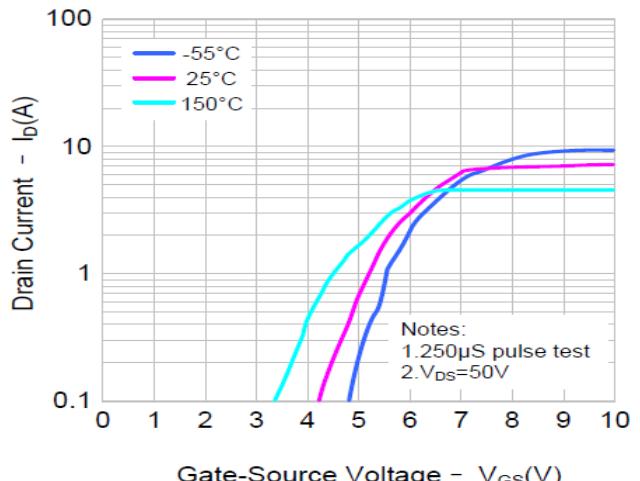


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

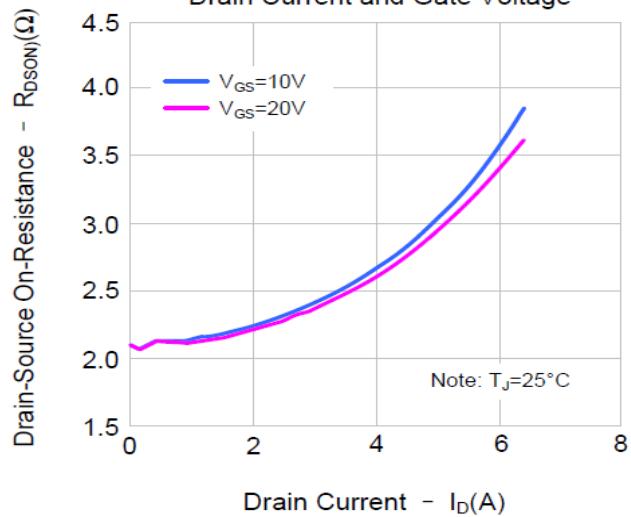


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

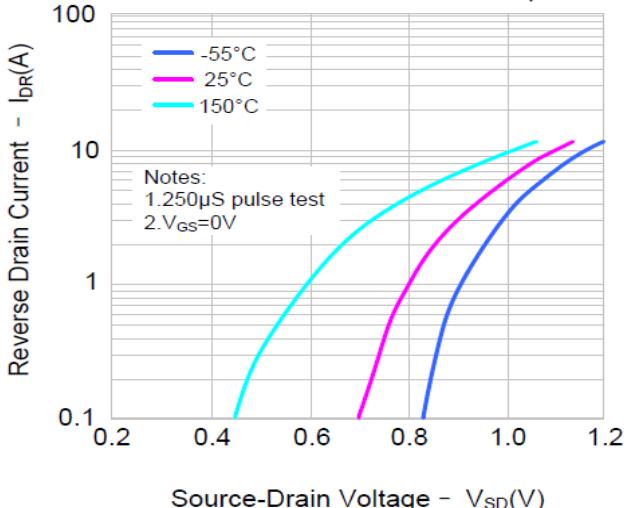


Figure 5. Capacitance Characteristics

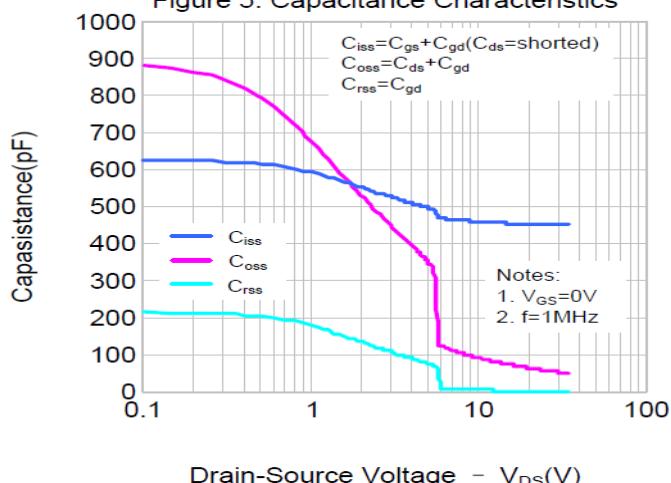
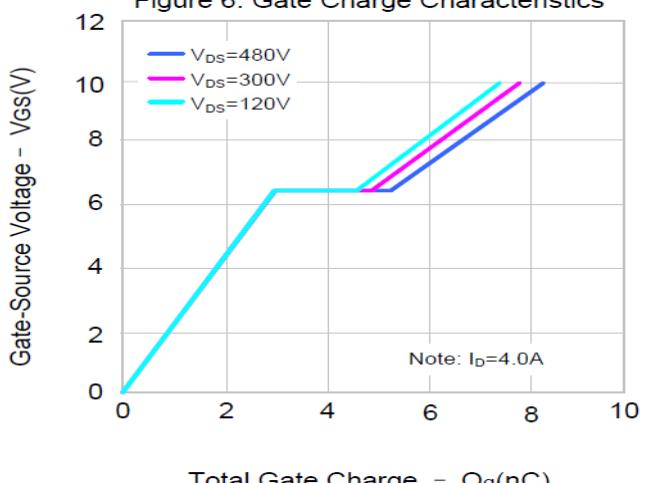


Figure 6. Gate Charge Characteristics



CHARACTERISTIC CURVES

Figure 7. Breakdown Voltage Variation vs. Temperature

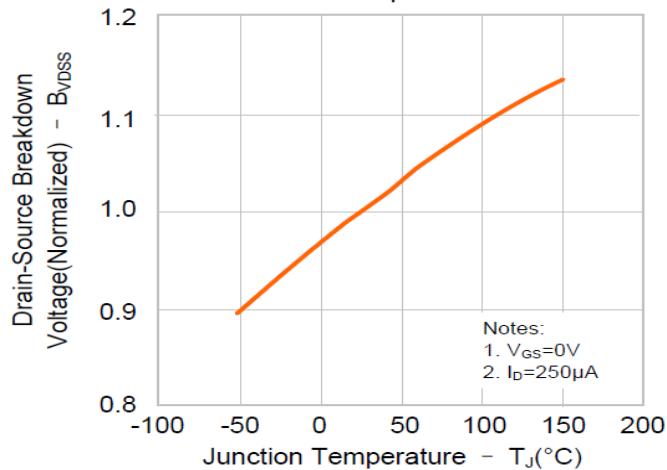


Figure 8. On-resistance Variation vs. Temperature

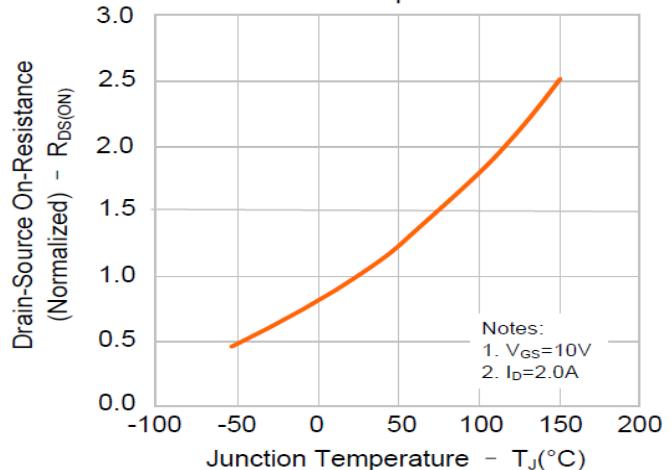


Figure 9 Max. Safe Operating Area

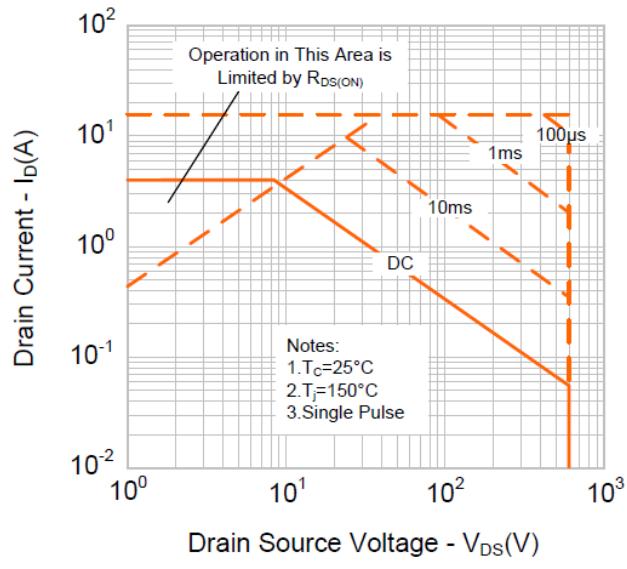
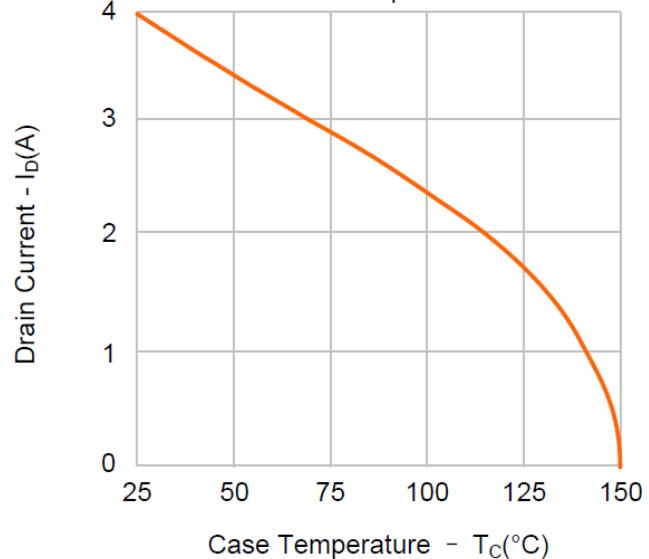
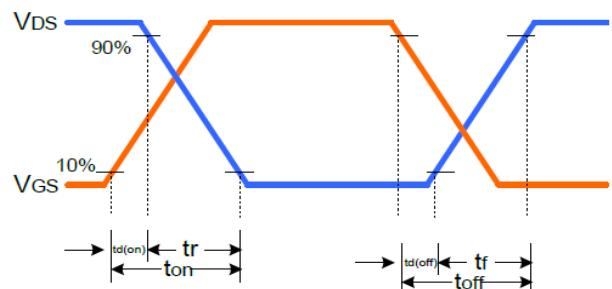
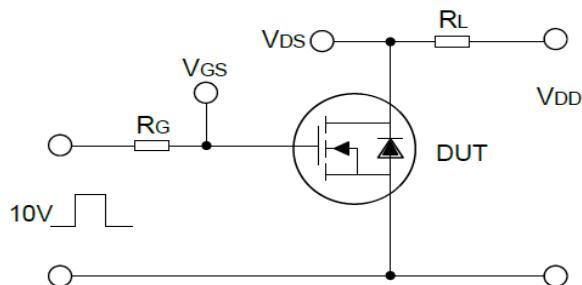


Figure 10. Maximum Drain Current vs. Case Temperature

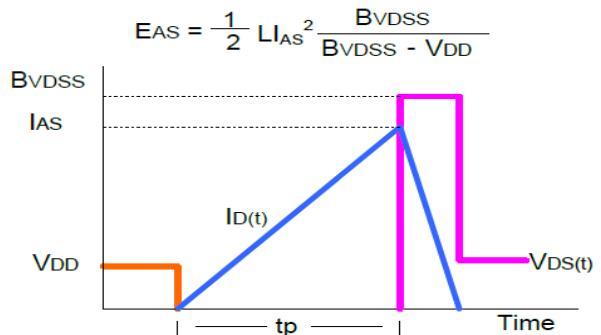
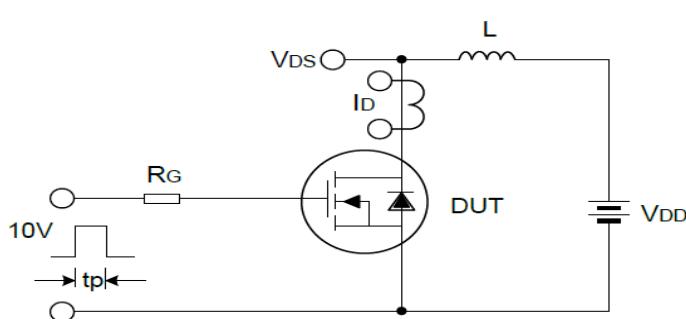


TYPICAL TEST CURVES

Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform



Gate Charge Test Circuit & Waveform

